IPC ASSOCIATION OF ELECTRONICS I	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both nternational and Pan-American copyright conventions.		nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowel parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia				Materials and I	als and Mfg Information			
upplier l	Information													
Company name*			Company unique ID			U	Unique ID Authority				Response Date*			
ısemi											2024-05-18			
ontact Nar	me	Title - Contac	Title - Contact			Phone - Contact*			Email	Email - Contact*				
roduct-En	v-Stewards	Product Enviro Compliance			1	NA			Produ	Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative			P	Phone - Representative*			Email	Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance			1	NA			Produ	Product-Env-Stewards@onsemi.com			
I	Requester Item Number Mfr Ite		n Number Mfr Item Name			Effective Date	Version	Manufacturing S	ite	Weight*	UOM	Unit Type		
		FGH4L′	75T65MQDC5	650V 75A FS4 Hy (TO247-4L)	brid IGBT Indu	ıstrial	2024-05-18		СРА		6378.738	mg	Each	
lanufact	turing Process Informa	ation												
Т	Terminal Plating / Grid Array Material		Cerminal Base Alloy J-STD-020 MS		-STD-020 MSL	Rating	Peak Process Body Temperature Max Time at Pea			Peak Temper	k Temperature Number of Reflow Cycles			
Matte Tin (Sn) - annealed		CU Alloy NA		IA		0	C	30	seco	onds 3				
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RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier shall apply the information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	5.658	mg	Supplier	Silicon Carbide	409-21-2		5.658	mg
			Supplier	Silicon (Si)	7440-21-3		0	mg
Die Attach Solder	7.49	mg	Supplier	Silver (Ag)	7440-22-4		0.1873	mg
			A	Lead (Pb)	7439-92-1	7a	6.9282	mg
			Supplier	Tin (Sn)	7440-31-5		0.3745	mg
Lead Frame	3982.39	mg	В	Nickel (Ni)	7440-02-0		9.5577	mg
			Supplier	Iron (Fe)	7439-89-6		5.9736	mg
			Supplier	Copper (Cu)	7440-50-8		3965.2656	mg
			Supplier	Phosphorus (P)	7723-14-0		1.593	mg
Mold Compound-Black	2349.04	mg		Epoxy resin	proprietary data		70.4712	mg
			Supplier	Phenolic Resin	Proprietary Data		35.2356	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		352.356	mg
			Supplier	Carbon Black (C)	1333-86-4		11.7452	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1879.2321	mg
Plating	23.4	mg	Supplier	Tin (Sn)	7440-31-5		23.4	mg
Wire Bond - Al	10.76	mg	Supplier	Aluminum (Al)	7429-90-5		10.76	mg